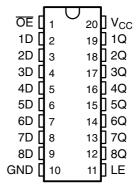
SN54LVT573, SN74LVT573 3.3-V ABT OCTAL TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS

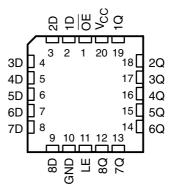
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- State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low Static Power Dissipation
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- Support Unregulated Battery Operation Down to 2.7 V
- Typical V_{OLP} (Output Ground Bounce)
 < 0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Bus-Hold Data Inputs Eliminate the Need for External Pullup Resistors
- Support Live Insertion
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Packages, and Ceramic (J) DIPs

SN54LVT573 . . . J OR W PACKAGE SN74LVT573 . . . DB, DW, OR PW PACKAGE (TOP VIEW)



SN54LVT573 . . . FK PACKAGE (TOP VIEW)



description

These octal latches are designed specifically for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

The eight latches of the 'LVT573 are transparent D-type latches. While the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the logic levels set up at the D inputs.

A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components. \overline{OE} does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74LVT573 is available in Tl's shrink small-outline package (DB), which provides the same I/O pin count and functionality of standard small-outline packages in less than half the printed-circuit-board area.

The SN54LVT573 is characterized for operation over the full military temperature range of -55° C to 125° C. The SN74LVT573 is characterized for operation from -40° C to 85° C.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



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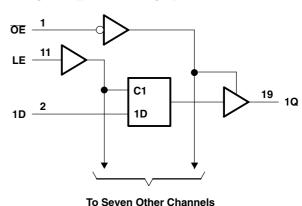
FUNCTION TABLE (each latch)

	INPUTS		OUTPUT
OE	LE	D	Q
L	Н	Н	Н
L	Н	L	L
L	L	Χ	Q_0
Н	X	Χ	Z

logic symbol[†]

ΟE ΕN 11 LE C1 2 19 1D ∇ 1Q 3 18 2D 2Q 4 17 3Q 3D 5 16 4Q 4D 6 15 5D 5Q 14 6D 6Q 8 13 7D 9 12 8D 8Q

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[‡]

Supply voltage range, V _{CC}	0.5 V to 4.6 V
Input voltage range, V _I (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high state or power-off state, V _O (see Note 1)	0.5 V to 7 V
Current into any output in the low state, Io: SN54LVT573	
SN74LVT573	128 mA
Current into any output in the high state, I _O (see Note 2): SN54LVT573	48 mA
SN74LVT573	64 mA
Input clamp current, I _{IK} (V _I < 0)	–50 mA
Output clamp current, I_{OK} ($V_O < 0$)	–50 mA
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 3): DB package	0.6 W
DW package	1.6 W
PW package	
Storage temperature range, T _{stq}	

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 - 2. This current flows only when the output is in the high state and $V_O > V_{CC}$.
 - The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the Package Thermal Considerations application note in the 1994 ABT Advanced BiCMOS Technology Data Book, literature number SCBD002B.



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

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recommended operating conditions (see Note 4)

			SN54L	/T573	SN74L	/T573	UNIT
			MIN	MAX	MIN	MAX	UNII
V _{CC}	Supply voltage		2.7	3.6	2.7	3.6	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		8.0	V
VI	Input voltage			5.5		5.5	V
I _{OH}	High-level output current			-24		-32	mA
I _{OL}	Low-level output current			48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
T _A	Operating free-air temperature		-55	125	-40	85	°C

NOTE 4: Unused control inputs must be held high or low to prevent them from floating.

SN54LVT573, SN74LVT573 3.3-V ABT OCTAL TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	_	SN	54LVT5	73	SN	74LVT5	73			
PARAMETER	Ι Τ	EST CONDITIONS		MIN	TYP†	MAX	MIN	TYP†	MAX	UNIT
V_{IK}	$V_{CC} = 2.7 \text{ V},$	$I_I = -18 \text{ mA}$				-1.2			-1.2	V
	$V_{CC} = MIN \text{ to } MAX^{\ddagger},$	$I_{OH} = -100 \mu A$		V _{CC} -0.	.2		V _{CC} -0	.2		
.,	$V_{CC} = 2.7 \text{ V},$	$I_{OH} = -8 \text{ mA}$		2.4			2.4			٧
V_{OH}	V 0V	$I_{OH} = -24 \text{ mA}$	2						V	
	V _{CC} = 3 V	$I_{OH} = -32 \text{ mA}$					2			
	V 07V	$I_{OL} = 100 \mu A$				0.2			0.2	
	$V_{CC} = 2.7 \text{ V}$	I _{OL} = 24 mA			0.5			0.5		
.,		I _{OL} = 16 mA				0.4			0.4	.,
V_{OL}	, ov	I _{OL} = 32 mA				0.5			0.5	V
	V _{CC} = 3 V	I _{OL} = 48 mA		0.55						
		I _{OL} = 64 mA						0.55		
	$V_{CC} = 0$ or MAX^{\ddagger} ,	V _I = 5.5 V				50			10	
l _i	.,	V _I = V _{CC} or GND	Control inputs			±1			±1	μΑ
·	$V_{CC} = 3.6 \text{ V}$	$V_I = V_{CC}$				1			1	•
		$V_I = 0$	Data inputs	-5		-5		-5		
I _{off}	$V_{CC} = 0$,	V_{I} or $V_{O} = 0$ to 4.5 V	-						±100	μΑ
	V 0V	$V_{I} = 0.8 V$	Data innuta	75			75			A
l _{l(hold)}	V _{CC} = 3 V	V _I = 2 V	Data inputs	-75			-75			μΑ
I _{OZH}	$V_{CC} = 3.6 \text{ V},$	V _O = 3 V				1			1	μΑ
I_{OZL}	$V_{CC} = 3.6 \text{ V},$	$V_0 = 0.5 V$				-1			-1	μΑ
			Outputs high		0.13	0.39		0.13	0.19	
Icc	$V_{CC} = 3.6 \text{ V},$	$I_{O}=0$,	Outputs low		8.6	14		8.6	12	mA
icc	$V_I = V_{CC}$ or GND	Outputs disabled		0.13	0.39		0.13	0.19	ША	
Δl _{CC} §		$_{\rm C}$ = 3 V to 3.6 V, One input at V $_{\rm CC}$ – 0.6 V, ner inputs at V $_{\rm CC}$ or GND				0.3			0.2	mA
C _i	V _I = 3 V or 0				4			4		pF
Co	V _O = 3 V or 0				8			8	_	pF

 $^{^{\}dagger}$ All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

		SN54LVT573								
		V _{CC} = ± 0.3	3.3 V 3 V	V _{CC} =	2.7 V	V _{CC} = ± 0.3	3.3 V 3 V	V _{CC} =	2.7 V	UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _w	Pulse duration, LE high	3.3		3.3		3.3		3.3		ns
t _{su}	Setup time, data before LE↓	1		0.9		0.7		0.6		ns
t _h	Hold time, data after LE↓	1.8		2		1.6		1.8		ns



[‡] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[§] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

SN54LVT573, SN74LVT573 3.3-V ABT OCTAL TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS

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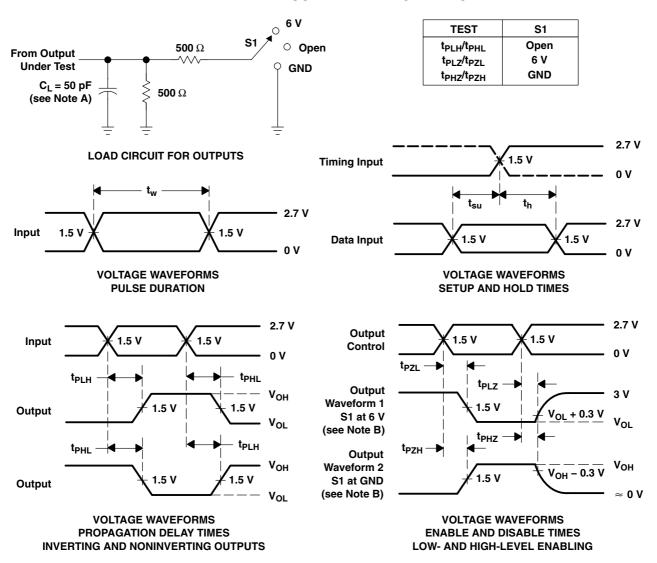
switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

				SN54L	VT573			SN	74LVT5	73				
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 3.3 V \pm 0.3 V		V _{CC} = 2.7 V		V_{CC} = 3.3 V \pm 0.3 V			V _{CC} = 2.7 V		UNIT		
			MIN	MAX	MIN	MAX	MIN	TYP†	MAX	MIN	MAX			
t _{PLH}	D	0	0.5	4.7		4.9	1	2.5	4.2		4.7	20		
t _{PHL}	D	Q	0.5	4.9		5.4	1	2.7	4.3		5.2	ns		
t _{PLH}	LE	0	1	6		6.9	1.6	3.5	5.6		6.3			
t _{PHL}	LE	Q	1.4	6.9		7.6	2.5	4.3	6.5		7.2	ns 2		
t _{PZH}	ŌĒ	0	0.5	5.3		6.4	1	2.8	5.1		6.2			
t _{PZL}	OE .	Q	0.7	5.7		7.2	1.3	3.3	5.5		6.6	ns		
t _{PHZ}	OF.	0	1.2	5.9		6.9	2	3.7	5.7		6.7	20		
t _{PLZ}	ŌĒ	Q	Q	Q	1	5.4		5.5	1.5	3	4.6		5.1	ns

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C₁ includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50 \Omega$, $t_f \leq 2.5 \text{ ns.}$
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





PACKAGE OPTION ADDENDUM

10-Dec-2020

PACKAGING INFORMATION

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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LVT573DW	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVT573	Samples
SN74LVT573PWR	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LX573	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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10-Dec-2020

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





_		
		Dimension designed to accommodate the component width
		Dimension designed to accommodate the component length
		Dimension designed to accommodate the component thickness
	W	Overall width of the carrier tape
Γ	P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVT573PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVT573PWR	TSSOP	PW	20	2000	853.0	449.0	35.0

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



NOTES:

- All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
 C. Publication IPC-7351 is recommended for alternate design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.





SOIC



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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